

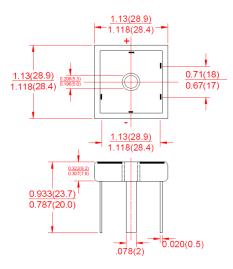
# 50A THREE-PHASE BRIDGE RECTIFIER

## **Features**

- Integrally molding heatsinks provide very low thermal resistancefor maximum heat dissipation
- Surge overload rating to 480 ampers
- High temperature soldering guaranteed:260 °C/10 second, at 5 lbs. (2.3kg) tension.

## **Mechanical Data**

- Case: Epoxy, molded plastic with heatsink integrally mounted in the bridge encapsulation.
- Mounting Position: Bolt down on heatsink with silicone thermal compound between bridge and mounting surface for maximum heat transfer efficiency
- Mounting Torque: 20 in. lbs max.
- Weight: 0.706 ounce, 20 grams



Dimensions in inches and (millimeters)

#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 cambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load derate current by 20%.

	SYMBOLS	XNDS5008	XNDS5012	XNDS5016	UNITS
Peak Repetitive Reverse Voltage	$V_{RRM}$	800	1200	1600	Volts
Working Peak Reverse Voltage	$V_{RWM}$	800	1200	1600	Volts
Maximum DC Blocking Voltage	V <sub>DC</sub>	800	1200	1600	Volts
Maximum Average Forward Rectified Output Current, at T <sub>C</sub> =72 °C(Note 2)	I <sub>(AV)</sub>	50			Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	480			Amps
Rating for Fusing(t<8.3ms)	I <sup>2</sup> T	1500			A <sup>2</sup> S
Maximum Instantaneous Forward Voltage drop per Bridge element at 19.5A	V <sub>F</sub>	1.15			Volts
Maximum DC Reverse Current at rated DC blocking voltage per element $T_j$ =150 $^{\circ}$ C	$I_R$	5.0			mA
Isolation Voltage from case to leads	Vso	2500			V <sub>AC</sub>
Typical Thermal Resistance per Element	$R_{\theta JC}$	1.6			°C/W
Operating Temperature Range	T <sub>J</sub>	-55 to +150			°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150			°C
NOTES:					

- 1. Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts.
- Unit mounted on 11. 8"×11.8"×0.6" thick (300×300×15mm) Copper plate.



### RATINGS AND CHARACTERISTIC CURVES

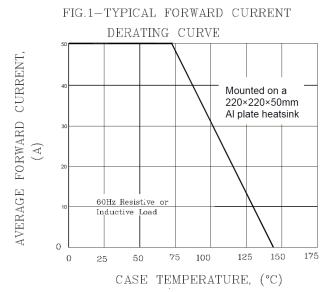


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE 50 AVERAGE FORWARD CURRENT, Mounted on a 40 8.66"×8.66"×1.9" Al plate heatsink 30 20 60Hz Resistive or 10 Inductive Load 0 175 0 25 50 55 AMBIENT TEMPERATURE, (°C)

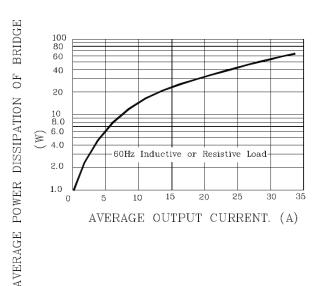


FIG. 4-MAXIMUM POWER DISSIPATION



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